

Summary

Method For Producing A Component Having Submerged Connecting Areas

5 To expose a submerged bondable terminal pad in a component that includes at least two substrates which are joined with each other, it is proposed that grooves of relatively shallow depth be provided on the connecting surface of the second substrate before the two substrates are joined. After the two substrates are joined, incisions are made opposite the grooves which open the grooves from the back side. The cutouts to be
10 removed are defined between two grooves.

Figure 4